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Field Device Integration (FDI) –
Part 4: FDI Packages

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Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

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CDV	Report on voting
65E/347/CDV	65E/424/RVC

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INTRODUCTION

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning

- a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;
- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
- d) extensible device object model, see Patent Family US12/893,680.

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FIELD DEVICE INTEGRATION (FDI) – Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

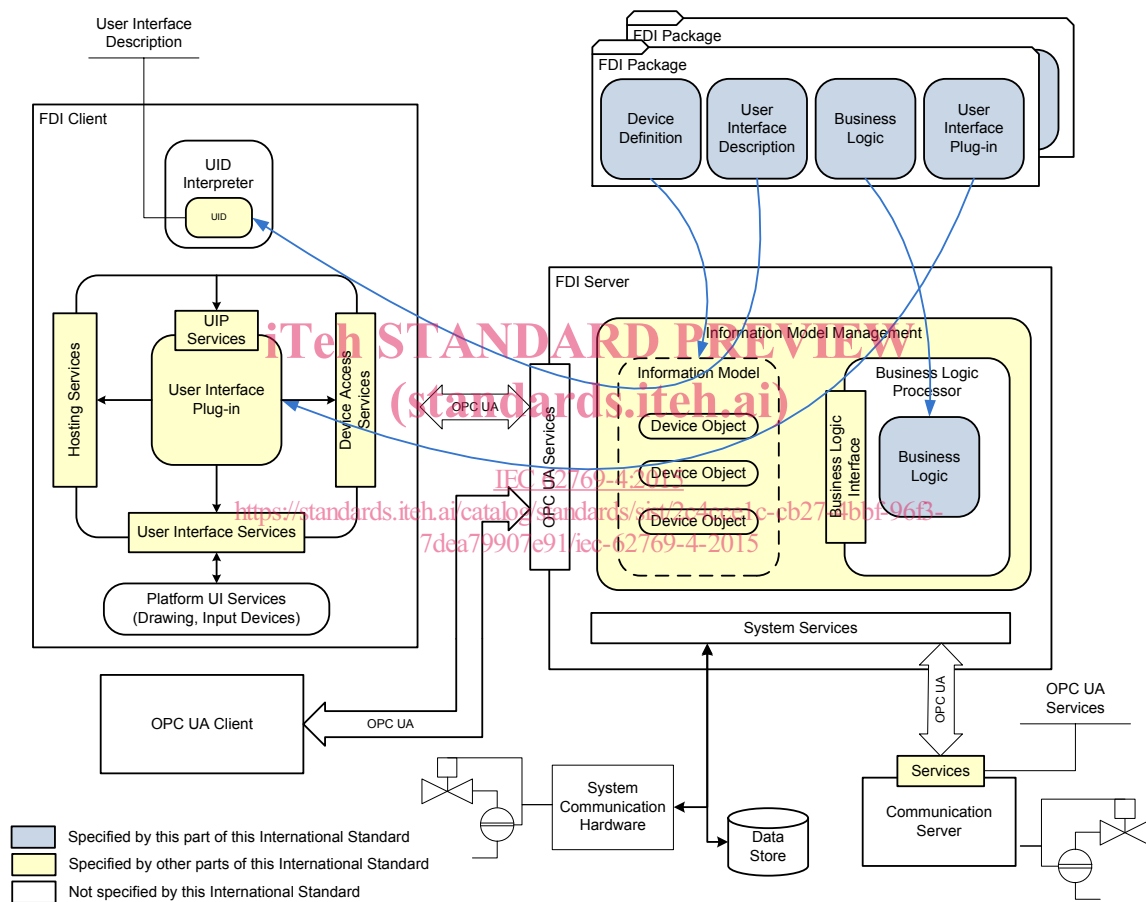


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 61804-3¹, *Function blocks (FB) for process control and Electronic Device Description Language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4:–2, *Function blocks (FB) for process control and Electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

NOTE IEC 62769-1 is technically identical to FDI-2021.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE IEC 62769-6 is technically identical to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE IEC 62769-7 is technically identical to FDI-2027.

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:2011, *Information technology – Document description and processing languages – Office Open XML File Formats – Part 2: Open Packaging Conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

Extensible Markup Language (XML) 1.0, W3C Recommendation, available at <<http://www.w3.org/TR/REC-xml/>>

XML Schema Definition Language (XSD) 1.1, W3C Recommendation, available at <<http://www.w3.org/TR/xmlschema11-1/>>

3 Terms, definitions, abbreviated terms and acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1, ISO/IEC 29500-2, and the following apply.

3.1.1

attachment

device and protocol specific support files that are not directly used to integrate the Device into the system

¹ To be published.

² To be published.

3.1.2

FDI Communication Package

FDI Package that provides information to integrate an FDI Communication Server to an FDI Server

Note 1 to entry: This note applies to the French language only.

3.1.3

FDI Device Package

FDI Package that provides one or more device types to an FDI Server

Note 1 to entry: This note applies to the French language only.

3.1.4

FDI Package Model

description of the structure and elements of an FDI Package

Note 1 to entry: This note applies to the French language only.

3.1.5

FDI Profile Package

FDI Package that provides information for creating a device type node that can be associated with a class of devices

Note 1 to entry: This note applies to the French language only.

3.1.6

FDI Registration Authority

entity, which has the right and the ability to perform FDI conformance tests on FDI Packages and to issue registration certificate documents

3.1.7

FDI UIP Package

FDI Package that provides one or more UIPs to an FDI Server

Note 1 to entry: This note applies to the French language only.

Note 2 to entry: This note applies to the French language only.

3.1.8

Package Catalog

file that describes the contents of an FDI Package

Note 1 to entry: This note applies to the French language only.

3.1.9

UIP Catalog

file that describes the properties of a UIP

Note 1 to entry: This note applies to the French language only.

3.1.10

UIP Variant

platform specific element of a User Interface Plug-in

Note 1 to entry: A UIP is composed of one or more variants. For example, one variant may be optimized for portable devices while another variant is optimized for large screen devices.

Note 2 to entry: This note applies to the French language only.

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